

# DATA SHEET

## **T2322B** Triacs logic level

Product specification

October 2001

# Triacs logic level

# T2322B

## GENERAL DESCRIPTION

Passivated, sensitive gate triac in a plastic envelope, intended for use in general purpose bidirectional switching and phase control applications. This device is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

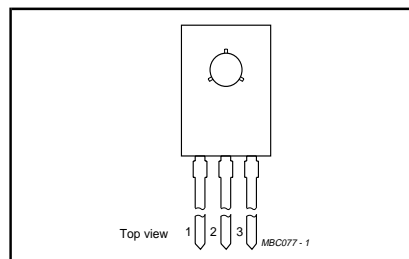
## QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
$V_{DRM}$	Repetitive peak off-state voltages	200	V
$I_{T(RMS)}$	RMS on-state current	2.5	A
$I_{TSM}$	Non-repetitive peak on-state current	27	A

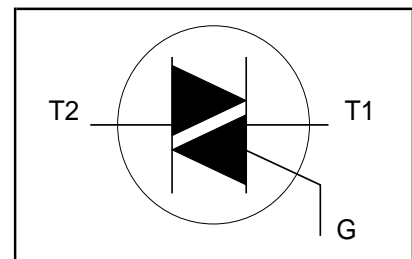
## PINNING - SOT32

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate

## PIN CONFIGURATION



## SYMBOL



## LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DRM}$	Repetitive peak off-state voltages		-	200 <sup>1</sup>	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 107\text{ }^\circ\text{C}$	-	2.5	A
$I_{TSM}$	Non-repetitive peak on-state current	full sine wave; $T_j = 25\text{ }^\circ\text{C}$ prior to surge $t = 20\text{ ms}$	-	25	A
		$t = 16.7\text{ ms}$	-	27	A
$I^2t$	$I^2t$ for fusing	$t = 10\text{ ms}$	-	3.1	A <sup>2</sup> s
$di_T/dt$	Repetitive rate of rise of on-state current after triggering	$I_{TM} = 6\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $di_G/dt = 0.2\text{ A}/\mu\text{s}$			
		T2+ G+	-	50	A/ $\mu\text{s}$
		T2+ G-	-	50	A/ $\mu\text{s}$
		T2- G-	-	50	A/ $\mu\text{s}$
		T2- G+	-	10	A/ $\mu\text{s}$
$I_{GM}$	Peak gate current		-	2	A
$V_{GM}$	Peak gate voltage		-	5	V
$P_{GM}$	Peak gate power		-	5	W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.5	W
$T_{stg}$	Storage temperature		-40	150	$^\circ\text{C}$
$T_j$	Operating junction temperature		-	125	$^\circ\text{C}$

<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 3 A/ $\mu\text{s}$ .

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**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base	full cycle	-	-	3.0	K/W
		half cycle	-	-	3.7	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	in free air	-	-	95	K/W

**STATIC CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{GT}$	Gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$				
		T2+ G+	-	2.0	5	mA
		T2+ G-	-	2.5	5	mA
		T2- G-	-	2.5	5	mA
		T2- G+	-	5.0	10	mA
$I_L$	Latching current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$				
		T2+ G+	-	1.6	10	mA
		T2+ G-	-	4.5	15	mA
		T2- G-	-	1.2	10	mA
		T2- G+	-	2.2	15	mA
$I_H$	Holding current	$V_D = 12\text{ V}; I_{GT} = 0.1\text{ A}$	-	1.2	10	mA
$V_T$	On-state voltage	$I_T = 5\text{ A}$	-	1.4	1.70	V
$V_{GT}$	Gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$	-	0.7	1.5	V
		$V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_j = 125\text{ °C}$	0.25	0.4	-	V
$I_D$	Off-state leakage current	$V_D = V_{DRM(max)}; T_j = 125\text{ °C}$	-	0.1	0.5	mA

**DYNAMIC CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$dV_D/dt$	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 100\text{ °C};$ exponential waveform; $R_{GK} = 1\text{ k}\Omega$	-	100	-	V/ $\mu$ s
$t_{gt}$	Gate controlled turn-on time	$I_{TM} = 6\text{ A}; V_D = V_{DRM(max)}; I_G = 0.1\text{ A};$ $dI_G/dt = 5\text{ A}/\mu$ s	-	2	-	$\mu$ s

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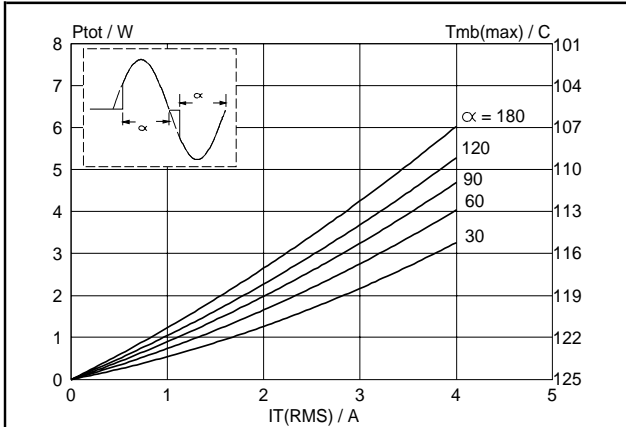


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus rms on-state current,  $I_{T(RMS)}$ , where  $\alpha$  = conduction angle.

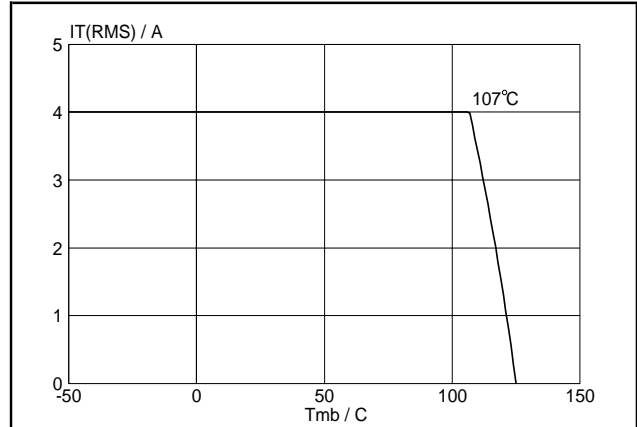


Fig.4. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

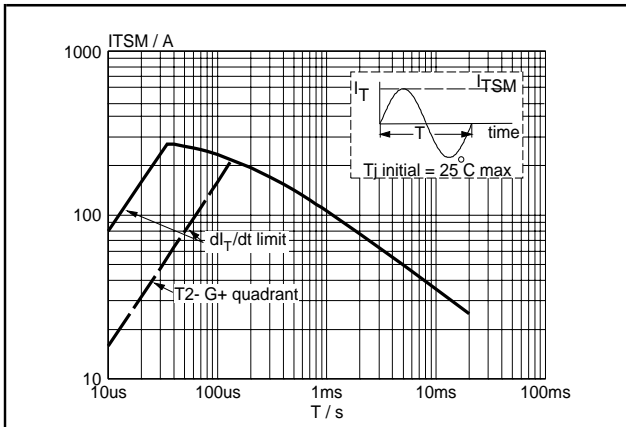


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \leq 20ms$ .

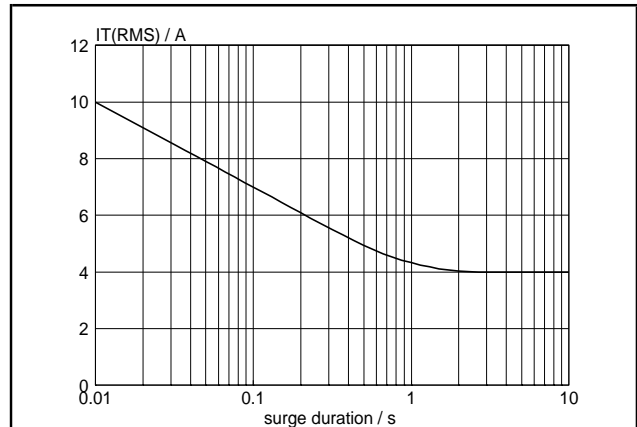


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents,  $f = 50\text{ Hz}$ ;  $T_{mb} \leq 107^\circ\text{C}$ .

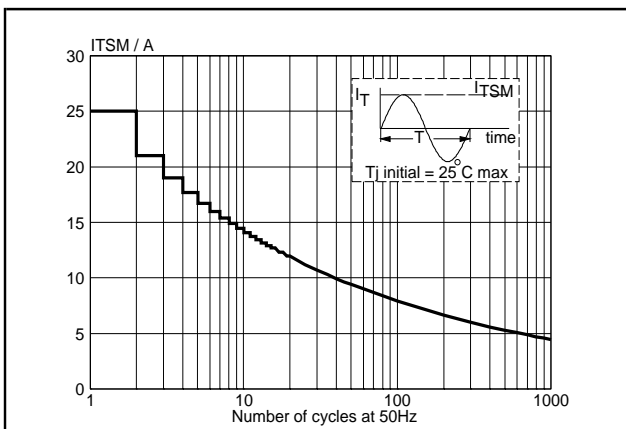


Fig.3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents,  $f = 50\text{ Hz}$ .

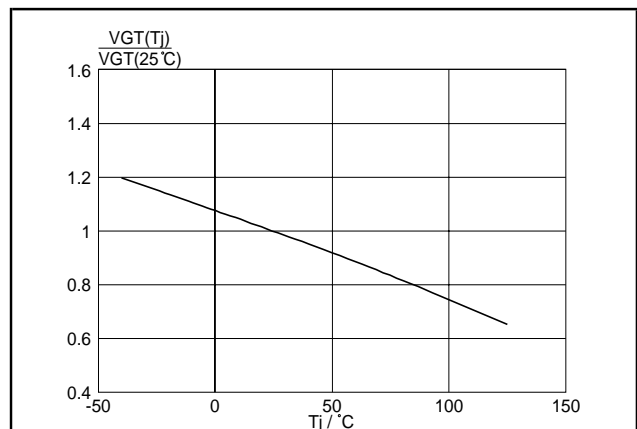
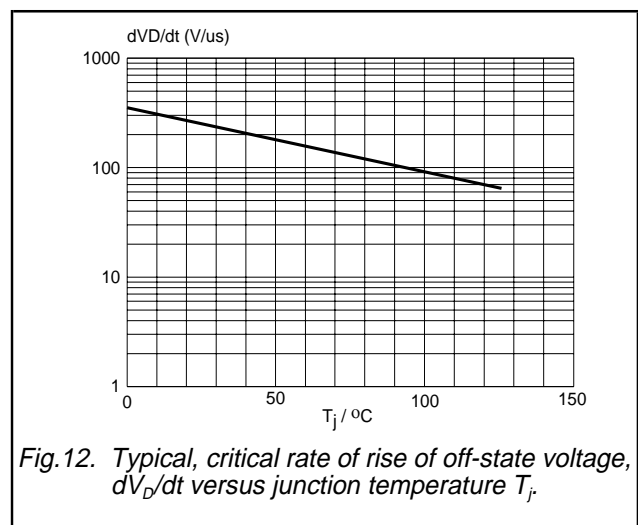
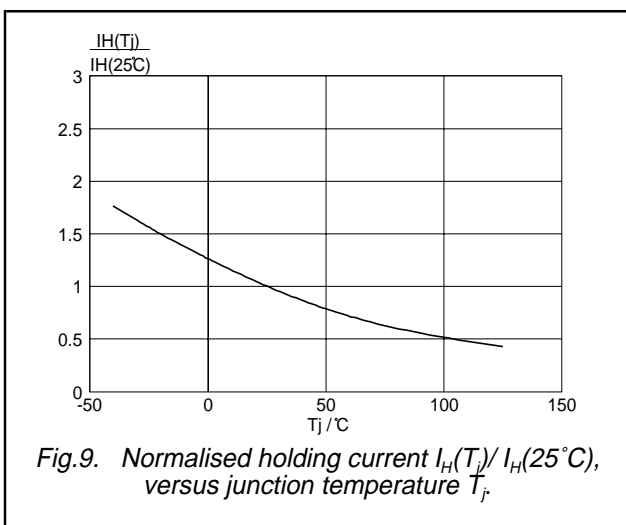
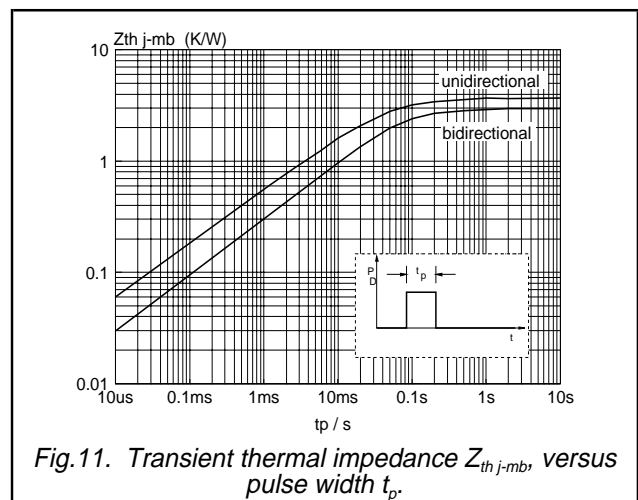
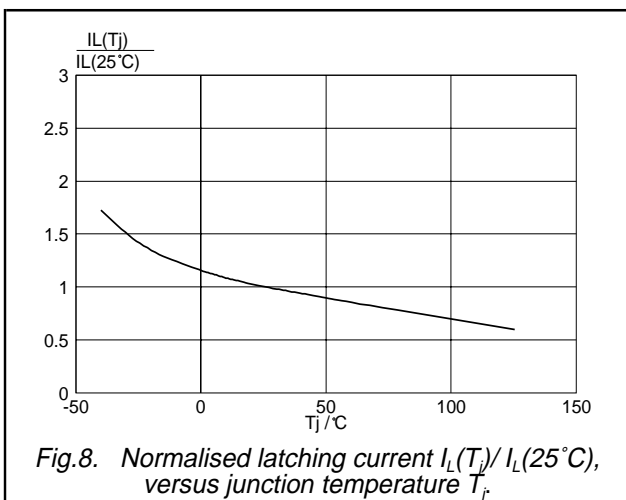
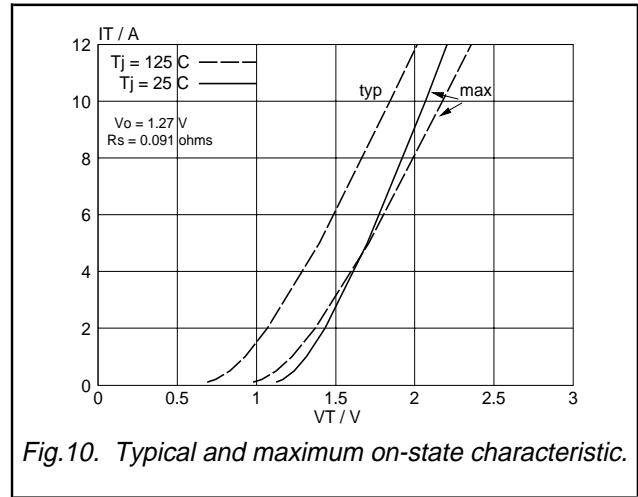
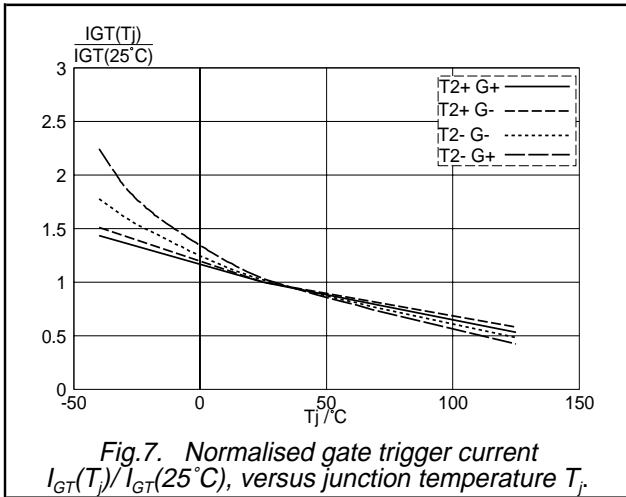


Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j) / V_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

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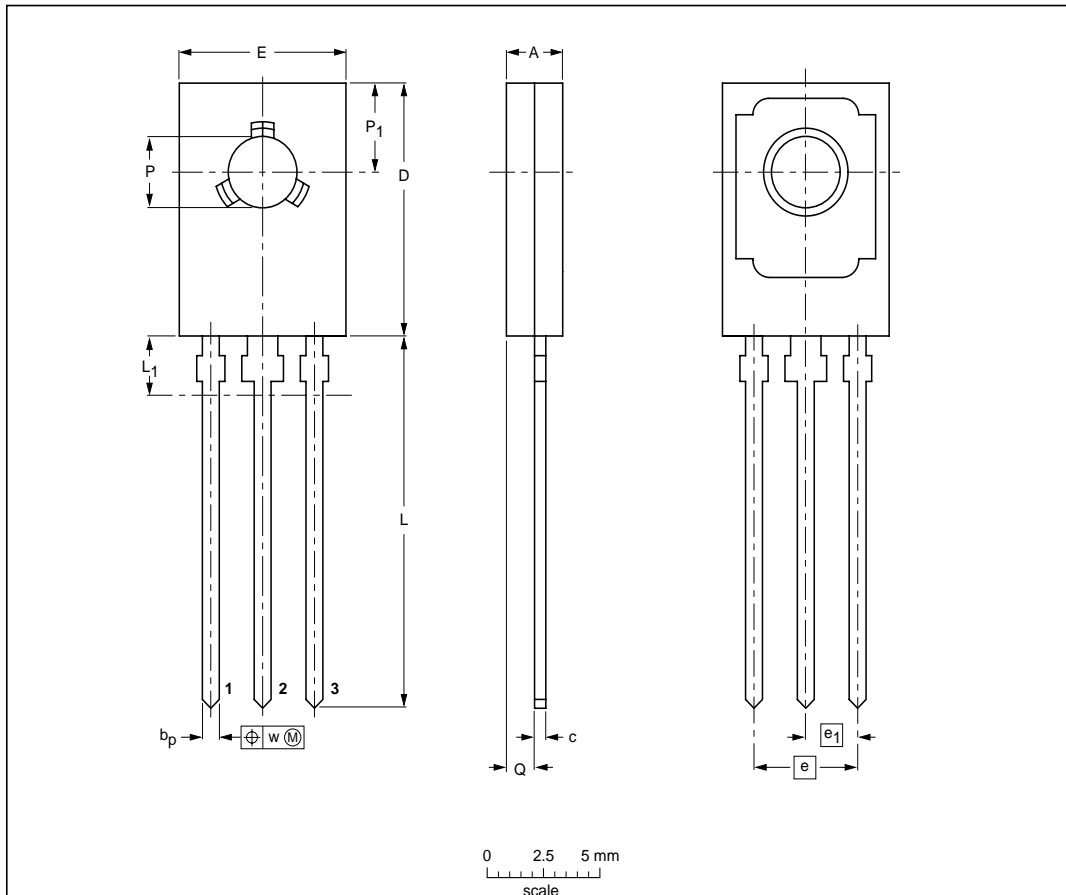
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**MECHANICAL DATA**

Dimensions in mm

Net Mass: 0.8 g

Plastic single-ended leaded (through hole) package; mountable to heatsink, 1 mounting hole; 3 leads SOT32



DIMENSIONS (mm are the original dimensions)

UNIT	A	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max	Q	P	P <sub>1</sub>	w
mm	2.7 2.3	0.88 0.65	0.60 0.45	11.1 10.5	7.8 7.2	4.58	2.29	16.5 15.3	2.54	1.5 0.9	3.2 3.0	3.9 3.6	0.254

**Note**

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT32		TO-126			97-03-04

Fig.13. SOT32.

**Notes**

1. Refer to mounting instructions for SOT32 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

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**DEFINITIONS**

<b>DATA SHEET STATUS</b>		
<b>DATA SHEET STATUS<sup>2</sup></b>	<b>PRODUCT STATUS<sup>3</sup></b>	<b>DEFINITIONS</b>
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<b>Application information</b>		
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For sales offices addresses send e-mail to: [sales.addresses@www.semiconductors.philips.com](mailto:sales.addresses@www.semiconductors.philips.com).

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Printed in The Netherlands

XXXXXX/700/01/pp8

Date of release: October 2001

Document order number: 9397 750 09038

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